

IEEE Radio and Wireless Symposium

18-21 January 2026 - Loews Hollywood Hotel - Los Angeles, CA, USA



Part of Radio and Wireless Week

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Call For Papers

The 2026 IEEE Radio and Wireless Symposium (RWS 2026) will be held during the week of 18–21 January 2026 at the Loews Hollywood Hotel – Los Angeles, CA, USA. RWS 2026 and the IEEE Topical Meeting on Silicon Monolithic Integrated Circuits (SiRF 2026) are co-located and will continue to hold joint sessions. Topical conferences held in parallel provide more focused sessions in the areas of RF Power Amplifiers (PAWR), Wireless Sensors and Sensor Networks (WiSNet), and Space Hardware and Radio (SHaRC). The RWW Demonstration Track provides an interactive forum for hands-on demonstration of the latest wireless experiments and innovations. There are also Special Sessions, Short Courses, and Workshops. RWS Papers featuring innovative work are solicited in (but not limited to) the following areas:

1. High-speed and Broadband Wireless Technologies

- Broadband Fixed Wireless and Last-Mile Access
- Optical Networks Systems and Microwave Photonics
- M2M, V2V & V2x Technologies & Applications

2. Emerging Wireless Technologies & Novel Engineered Materials / Processes

- Green, Sustainable Wireless Technologies & Networks
- Wireless Power Transfer
- Quantum Technologies
- Additive 3D manufacturing & Novel Engineered Materials

3. Wireless System Architecture and Propagation Channel Modeling

- Distributed & Ad-Hoc Network Architectures and Systems
- Wireless Mesh and Local/Personal/Body Area Networks

4. Wireless Digital Signal Processing and Artificial Intelligence

- Digital/Analog Adaptive/Collaborative Signal Processing
- Dynamic Spectrum Sharing, Coexistence, Interoperability
- Artificial Intelligence & Machine Learning in Radio and Wireless

5. Applications to Bio-Medical, Environmental, and Internet of Things

- Miniaturization and Integration of Wireless Technologies
- Biological Material Characterization
- Wireless Positioning Technologies & Remote Sensing

6. Antenna Technologies, MIMO and Multi-Antenna Communications

- Multi-Beam Smart Antennas
- Miniaturized, Multi-frequency and Broadband Antennas
- Passive and Active Antennas from RF to THz Frequencies
- Wireless Platform Integrated Antennas

7. Passive Components & Packaging

- · 3D-Packaging, Interconnects, and Applications
- Discrete, Embedded and Distributed Passive Components, Filters Couplers and Signal Separation Devices

8. MM-Wave to THz Systems & Applications

Paper submission instructions can be found at www.radiowirelessweek.org. Submissions should be formatted according to the submission review template available on the RWW website. Authors should indicate preference for oral or poster presentation. All submissions must be received by **23 July 2025**. All accepted papers will be published in a digest and presented papers will be included in the IEEE Xplore[®] Digital Library. Submissions will be evaluated based on novelty, significance of the work, technical content, interest to the audience, and quality of writing.